

AMENDMENTS TO THE CLAIMS

SUB
D17
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Claim 1 (currently amended): A wafer processing system comprising:
a load-lock having only a single wafer support for accommodating only a single wafer at a time, the load-lock having an integral cooling unit for cooling a wafer;
a transport module having a load chamber, a transfer chamber, and a pass-through chamber located between the load chamber and the transfer chamber, the load chamber being coupled to the load lock;
an intermediate process module coupled to the load chamber and the transfer chamber;
a first set of process modules coupled to the load chamber; and
a second set of process modules coupled to the transfer chamber.

Claim 2 (original): The system of claim 1 wherein a process module in the first set of process modules includes a pre-clean module.

Claim 3 (original): The system of claim 1 wherein a process module in the first set of process modules includes a physical vapor deposition module.

Claim 4 (original): The system of claim 1 wherein a process module in the first set of process modules includes a chemical vapor deposition module.

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Claim 5 (original): The system of claim 1 wherein a process module in the second set of process modules includes a pre-clean module.

Claim 6 (original): The system of claim 1 wherein a process module in the second set of process modules includes a chemical vapor deposition module.

Claim 7 (original): The system of claim 1 wherein a process module in the second set of process modules includes a physical vapor deposition module.

Claim 8 (original): The system of claim 1 wherein the single wafer support is a pedestal.

Claim 9 (original): The system of claim 1 wherein the intermediate process module is configured as a degas module.

Claim 10 (original): The system of claim 1 wherein the pass-through chamber is configured as a cooling station.

Claim 11 (original): The system of claim 1 wherein the intermediate process module is configured as a pre-clean module.

Claim 12 (original): The system of claim 1 wherein the intermediate process module is configured as a PVD module.

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Claim 13 (original): The system of claim 1 wherein the intermediate process module is configured as a CVD module.

Claims 14-16 (cancelled)

B3
Claim 17 (currently amended) A wafer processing system comprising:
a load lock having only a single wafer support, the single wafer support having an
integral cooling unit for cooling a wafer;
a transport module having a first chamber, a second chamber, and a pass-through
chamber between the first chamber and the second chamber, the first chamber being
coupled to the load lock;
an intermediate process module coupled to the first chamber;
a process module coupled to the first chamber; and
another process module coupled to the second chamber.

Claim 18 (cancelled)

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Claim 19 (currently amended): The system of claim 18 17 wherein the single wafer support is a water-cooled pedestal.

Claim 20 (original): The system of claim 17 wherein the intermediate process module is also coupled to the second chamber.

Claim 21 (original): The system of claim 17 wherein the pass-through chamber is configured as a cooling station.

Claims 22-24 (cancelled)